



Material Content Data Sheet



Sales Product Name		IPD50R950CE		Issued		1. August 2018		
MA#		MA001507158						
Package		PG-TO252-3-344		Weight*		322.16 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.820	0.56	0.56	5649	5649
leadframe	inorganic material	phosphorus	7723-14-0	0.043	0.01		134	
	non noble metal	iron	7439-89-6	0.144	0.04		447	
	non noble metal	copper	7440-50-8	143.904	44.68	44.73	446682	447263
	non noble metal	aluminium	7429-90-5	0.408	0.13	0.13	1266	1266
wire	non noble metal	aluminium	7429-90-5	0.408	0.13	0.13	1266	1266
encapsulation	organic material	carbon black	1333-86-4	0.685	0.21		2125	
	plastics	epoxy resin	-	18.488	5.74		57386	
	inorganic material	silicondioxide	60676-86-0	117.773	36.56	42.51	365572	425083
leadfinish	non noble metal	tin	7440-31-5	3.834	1.19	1.19	11899	11899
solder	non noble metal	tin	7440-31-5	0.041	0.01		126	
	noble metal	silver	7440-22-4	0.051	0.02		157	
	non noble metal	lead	7439-92-1	1.935	0.60	0.63	6006	6289
heatspreader	inorganic material	phosphorus	7723-14-0	0.010	0.00		31	
	non noble metal	iron	7439-89-6	0.033	0.01		103	
	non noble metal	copper	7440-50-8	32.995	10.24	10.25	102417	102551
*deviation	< 10%				Sum in total:		100.00	1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com